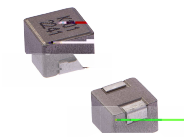
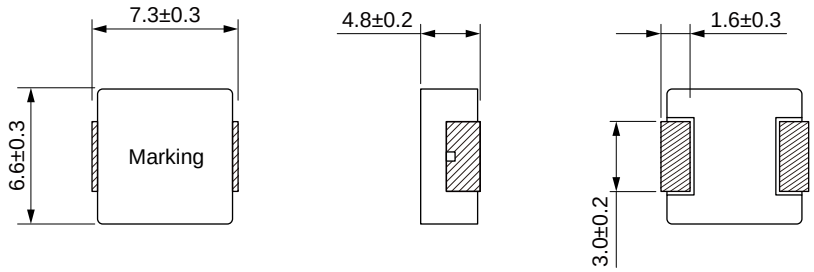
SMD Low Profile High Current Molded Inductor
Size 7050



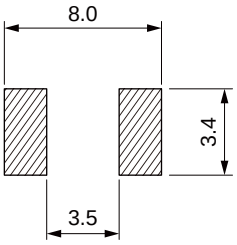
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Dimensions: [mm]



Land Pattern: [mm]

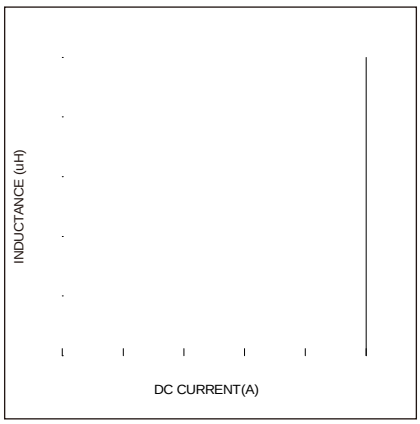


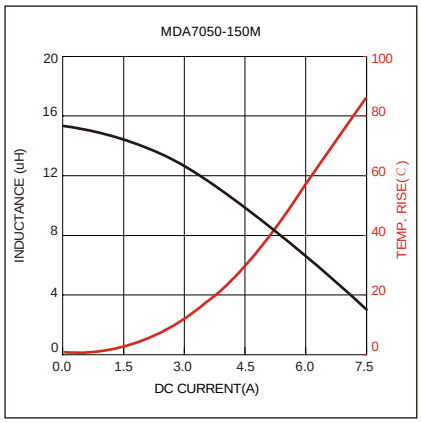
Electrical Properties:

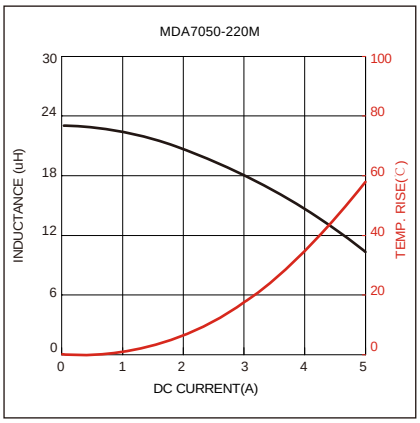
Part No	Inductance @ 100KHz/1V (µH)	Tolerance	Temperature Rise Current Typ. (A)	Temperature Rise Current Max. (A)	Saturation Current Typ. (A)	Saturation Current Max. (A)	DC Resistance Typ. (mΩ)	DC Resistance Max. (mΩ)

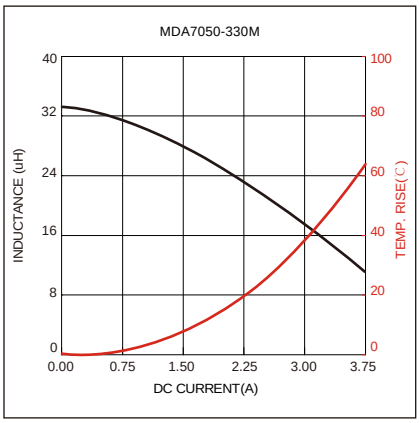
Part No	Inductance @ 100KHz/1V (μH)	Tolerance	Temperature Rise Current Typ. (A)	Saturation Current Typ. (A)	DC Resistance Typ. (mΩ)	DC Resistance Max. (mΩ)

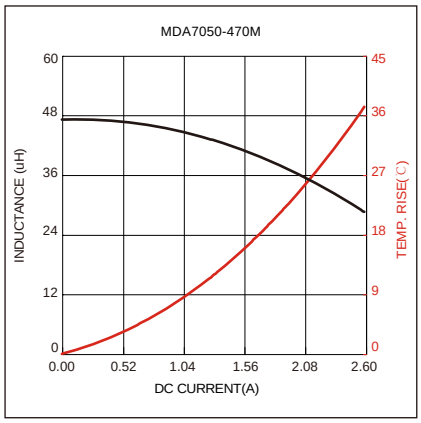
Typical Electrical Characteristics:



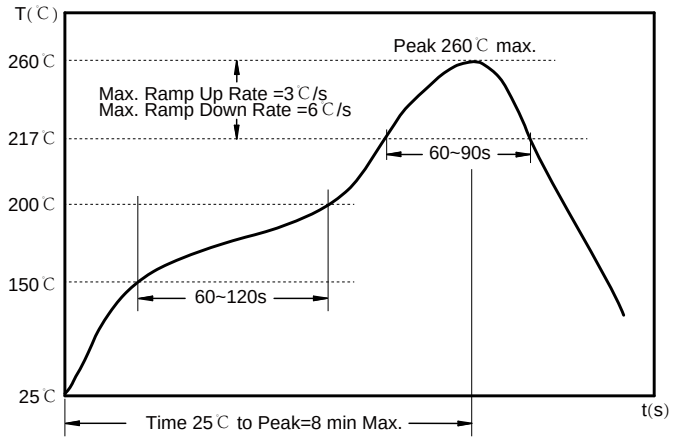

MDA7050-150M
INDUCTANCE (uH)
TEMP. RISE(℃)
DC CURRENT(A)
20
16
12
8
4
0
100
80
60
40
20
0
0.0
1.5
3.0
4.5
6.0
7.5


MDA7050-220M
INDUCTANCE (uH)
TEMP. RISE(℃)
DC CURRENT(A)
30
24
18
12
6
0
100
80
60
40
20
0
0
1
2
3
4
5


MDA7050-330M
INDUCTANCE (uH)
TEMP. RISE(℃)
DC CURRENT(A)
40
32
24
16
8
0
100
80
60
40
20
0
0.00
0.75
1.50
2.25
3.00
3.75


MDA7050-470M
INDUCTANCE (uH)
TEMP. RISE(℃)
DC CURRENT(A)
60
48
36
24
12
0
45
36
27
18
9
0
0.00
0.52
1.04
1.56
2.08
2.60

Soldering Reflow:



Preheat condition: 150 ~200℃/ 60~120 sec.

Allowed time above 217℃: 60~90 sec.

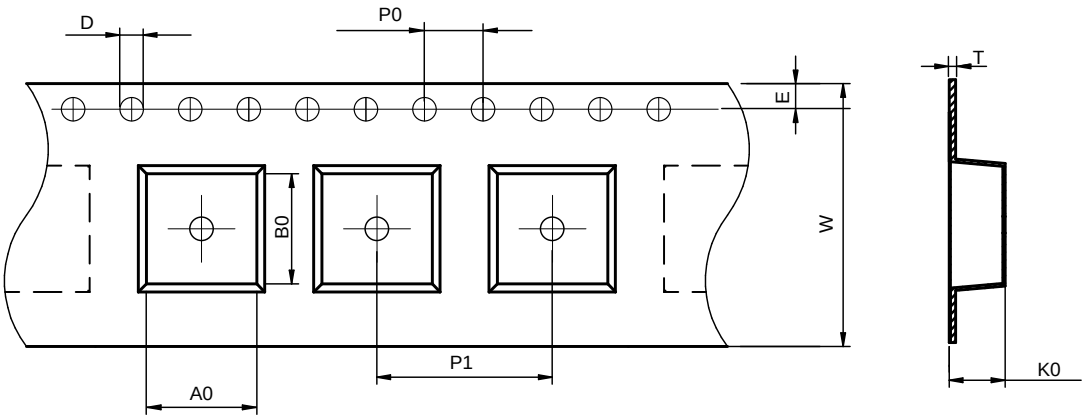
Max temperature: 260℃.

Max time at max temperature: 10 sec.

Allowed Reflow time: 2x max.

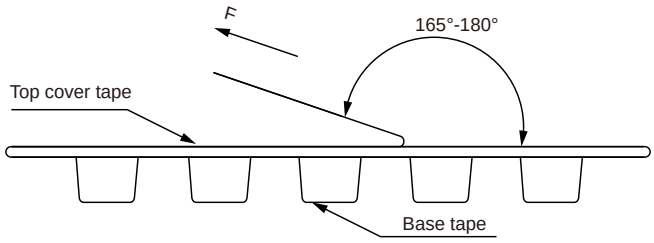
Packaging Information:

Tape Dimension:



Series	A0 (mm)	B0 (mm)	D (mm)	P0 (mm)	P1 (mm)	W (mm)	K0 (mm)	E (mm)	T (mm)
MDA7050	6.9±0.1	7.5±0.1	1.5±0.1	4.0±0.1	12.0±0.1	16.0±0.3	5.4±0.1	1.75±0.1	0.40±0.05

Peel force of top cover tape:

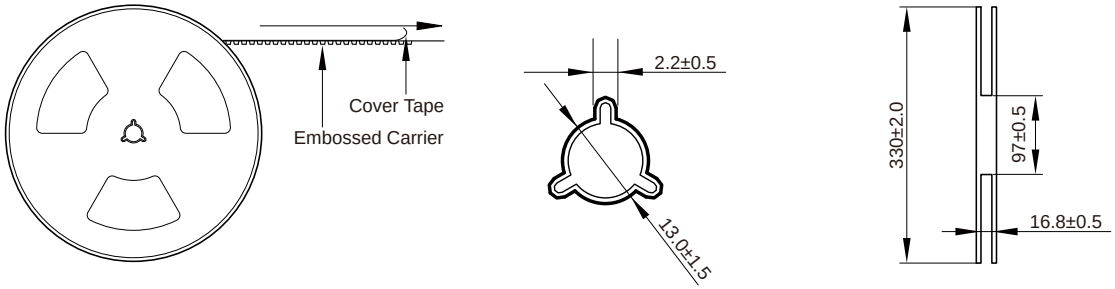


The peel force of top cover tape shall be between 0.1 to 1.3 N

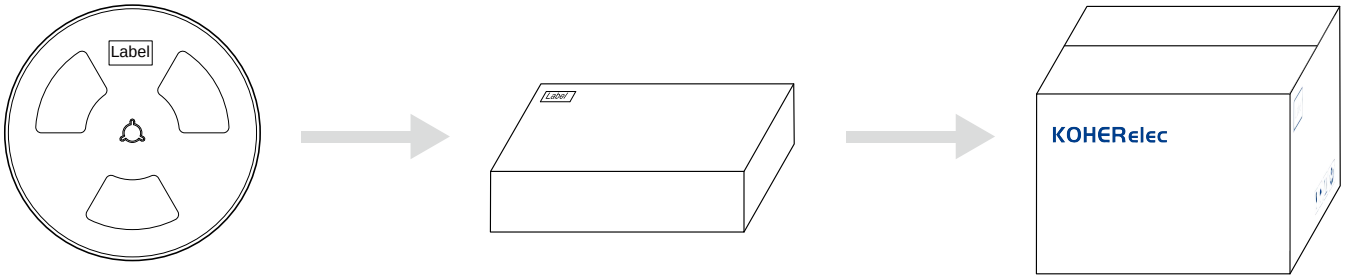
Product Marking:

Marking	K+Printing (Inductance+period)

Reel Dimension：[mm]



Packaging Quantity:



800 Pcs/Reel

2 Reel /Inner box(1600 Pcs)

3 Inner box/Carton box(4.8K Pcs)

Cautions and Warnings:

Storage Conditions：

- The storage period is within 12 months after the completion of production. Be sure to follow the storage conditions (temperature: -5 to 35°C, humidity: 75% RH Max).If the storage period elapses, the soldering of the terminal electrodes may deteriorate.The warranty period is one year.
- Product should not be exposed to environment with high temperature, high humidity, dust, corrosive gas and etc.
- Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- Please always handle products carefully to prevent any damage caused by dropping down or inappropriate removing.

Operation Instructions:

- Self heating (temperature increase) occurs when the power is turned ON, so the tolerance should be sufficient for the set thermal design.
- Before soldering, be sure to preheat components.The preheating temperature should be set so that the temperature difference between the solder temperature and chip temperature does not exceed 150°C.
- Soldering corrections after mounting should be within the range of the conditions determined in the specifications.If overheated, a short circuit, performance deterioration, or lifespan shortening may occur.
- Generally, Koher might not be familiar with either customer's specific application or actual requests as customer does.As a result customer shall be responsible for checking and confirming whether Koher product with the performance described in the product specification is suitable for using in customer's particular application or not.